300mm Fully-Automatic UV Irradiation System

RAD-2010F/12

Outline

- Fully-automatic UV irradiation system used for curing UV type dicing tape.
- Applicable for ring frame sizes used for 200mm and 300mm wafers.

Options
- Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
- Barcode Reader for Selecting Recipes
- Barcode Reader for Reading Ring Frame ID
- Visual Inspection Support System
- Double Loader/Unloader

Suitable Tapes
- Dicing tape: Adwill D series
- Dicing die bonding tape: Adwill LE Tape

External View

Facility

Power Supply
- Voltage: AC200-230V ±10% (AC190-253V)
- Frequency: 50/60Hz
- Phase: single phase
- Power consumption: 5.0kW

Air Supply
- Air pressure: 0.5-0.8MPa
- Air consumption: >300L/min (ANR)

Nitrogen Source
- Nitrogen pressure: 0.29MPa
- Nitrogen consumption: 30-50L/min (ANR)

Applicable Wafer Size
- 200mm, 300mm

Size
- Width: 1,650mm
- Depth: 1,200mm
- Height: 1,735mm (excluding the signal tower)

Weight
- 1,200kg

UPH
- 90 wafers/hour

The above processing capacity is based on following conditions:
- Wafer: 300mm diameter non-polished mirror wafer
- Ring frame: for 300mm wafer

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